



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IPP77N06S2-12	<b>Issued</b>	03. May 2021
<b>MA#</b>	MA000990634		
<b>Package</b>	PG-TO220-3-1	<b>Weight*</b>	2037.59 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.533	0.22	0.22	2225	2225
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		120	
	non noble metal	iron	7439-89-6	0.816	0.04		401	
	non noble metal	copper	7440-50-8	815.335	40.04	40.09	400145	400666
wire	non noble metal	aluminium	7429-90-5	8.278	0.41	0.41	4063	4063
encapsulation	inorganic material	zinc oxide	1314-13-2	5.929	0.29		2910	
	miscellaneous	miscellaneous	-	23.718	1.16		11640	
	plastics	epoxy resin	-	88.941	4.36		43650	
	inorganic material	silicon dioxide	60676-86-0	474.353	23.28	29.09	232801	291001
lead finish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10533	10533
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	120	121
solder	non noble metal	tin	7440-31-5	0.070			34	
	noble metal	silver	7440-22-4	0.088			43	
	non noble metal	lead	7439-92-1	3.345	0.16	0.16	1642	1719
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		87	
	non noble metal	iron	7439-89-6	0.590	0.03		290	
	non noble metal	copper	7440-50-8	589.466	28.93	28.97	289295	289672
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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